

Description

The PSC5425E combines a highly integrated switch-mode charger, to minimize single-cell Lithium-ion (Li-ion) charging time from a USB power source, and a boost regulator to power a USB peripheral from the battery. The charging parameters and operating modes are programmable through an I²C interface. The charger and boost regulator circuits switch at select-able frequency to lower the EMI and minimize the size of external passive components.

The PSC5425E provides battery charging in three phases: conditioning, constant current, and constant voltage. To ensure USB compliance and minimize charging time, the input current is limited to the value set through the I²C host. Charge termination current is programmable through the I²C host.

The integrated circuit (IC) automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode with leakage from the battery to the input prevented. Charge status is reported back to the host through the I²C port.

The PSC5425E can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery.

The PSC5425E is available in a 20-bump, 0.4mm pitch WLCSP package.

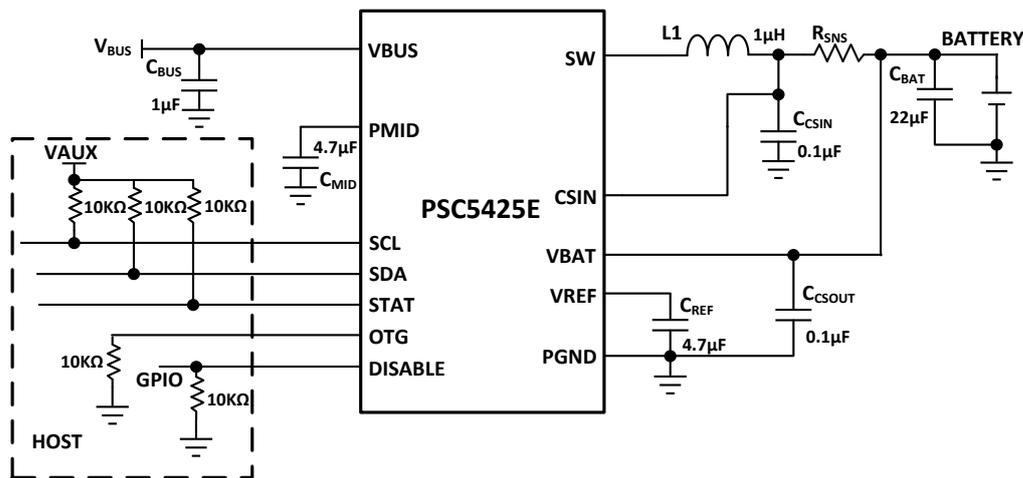


Figure 1: Typical Application

Feature

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-Ion and Li-Polymer Battery Packs
- Faster Charging than Linear
- Charge Voltage Accuracy: ±0.5% 25°C
- ±5% Charge Current Regulation Accuracy
- 29V Absolute Maximum Input Voltage
- 5.75V Maximum Input Operating Voltage
- 2.25A Maximum Charge Rate
- Programmable through I²C Interface:
 - Input Current
 - Fast-Charge/Termination Current
 - Charger Voltage
 - Termination Enable
- Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint 1µH External Inductor
- Weak Input Sources Accommodated by Reducing Charging Current to Maintain Minimum VBUS Voltage
- Low Reverse Leakage to Prevent Battery Drain to VBUS
- 5V, 700mA Boost Mode for USB OTG for 3.3 to 4.5V Battery Input

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Application

- Cellular Phones, Smart Phones, PDAs
- Tablet, Portable Media Players
- Gaming Device, Digital Cameras

Recommended External Components

Key Components	Recommended specification
L1	Inductor, 1.0-2.2uH, +/-20%, Isat>3A
C _{MID}	Capacitor, 4.7μF, +/-10%, Rated Voltage >6V
C _{REF}	Capacitor, 2.2μF, +/-10%, Rated Voltage >10V, 0402 or Capacitor, 4.7μF, +/-10%, Rated Voltage >6V, 0402
C _{BUS}	Capacitor, 1μF, +/-10%, Rated Voltage >30V

Block Diagram

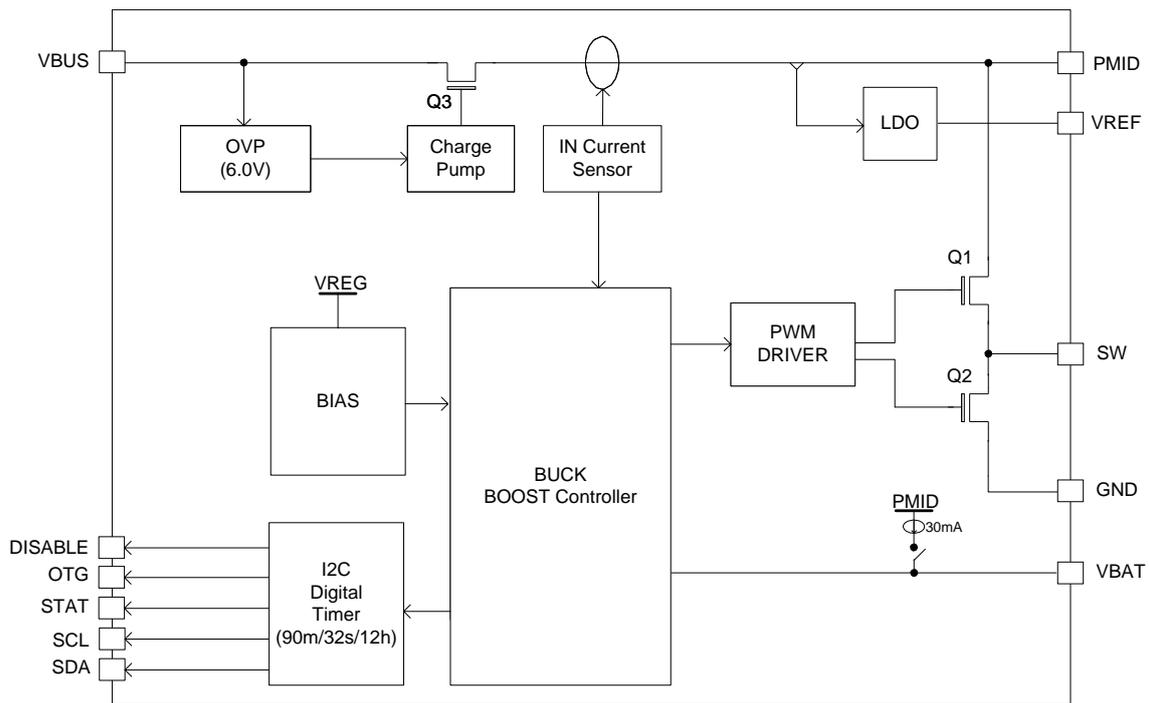
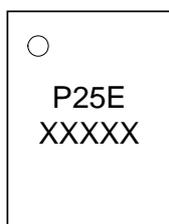


Figure 2: IC and System Block Diagram

Marking Information



P25E:PSC5425E
XXXXX: Production Tracing Code

Pin Configuration

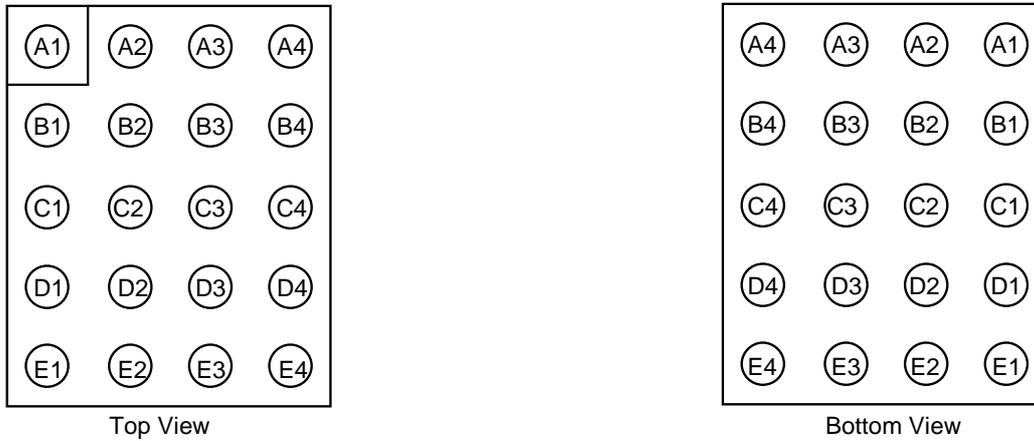


Figure 3: WLCSP-20 Pin Assignments

Pin Definitions

Pin#	Name	Description
A1,A2	VBUS	Charger Input Voltage and USB-OTG output voltage. Bypass with 1μF capacitor to PGND
A3	NC	NC.
A4	SCL	I²C Interface Serial Clock. This pin should not be left floating.
B1-B3	PMID	Power Input Voltage. Power input to the charger regulator, bypass point for the input current sense, and high-voltage input switch. Bypass with a minimum of 4.7μF, 10V capacitor to PGND.
B4	SDA	I²C Interface Serial Data. This pin should not be left floating.
C1-C3	SW	Switching Node. Connect to output inductor.
C4	STAT	Status. Open-drain output indicating charge status. The IC pulls this pin LOW when charge is in process.
D1-D3	PGND	Power Ground. Power return for gate drive and power transistors. The connection from this pin to the bottom of C _{MID} should be as short as possible.
D4	OTG	On-The-Go. Enables boost regulator in conjunction with OTG_EN and OTG_PL bits.
E1	CSIN	Current-Sense Input. Connect to the sense resistor in series with the battery. The IC uses this node to sense current into the battery. Bypass this pin with a 0.1μF capacitor to PGND.
E2	DISABLE	Charge Disable. If this pin is “1”, charging is disabled. When LOW, charging is controlled by I2C registers.
E3	VREF	Bias voltage. Connect to a 4.7uF capacitor to PGND. The output voltage is PMID, which is limited to 6.5V. Any resistor loading to VREF is NOT recommended.
E4	VBAT	Battery Voltage. Connect to the positive (+) terminal of the battery pack. Bypass with a 0.1μF capacitor to PGND if the battery is connected through long leads.

Maximum Ratings and Thermal Characteristics($T_A=25^\circ\text{C}$ unless otherwise noted)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Parameter		Symbol	Min.	Max.	Units
VBUS Voltage	Continuous	V_{BUS}	-0.7	29.0	V
	Pulsed, 100ms Maximum Non-Repetitive		-1.0		
STAT Voltage		V_{STAT}	-0.3	7.0	V
PMID Voltage		V_I		7.0	V
SW, CSIN, VBAT, VREF, DISABLE Voltage			-0.3	7.0	
Voltage on Other Pins		V_O	-0.3	6.5 ⁽¹⁾	V
Maximum VBUS Slope above 5.5V when Boost or Charger are Active		$\frac{dV_{BUS}}{dt}$		4	V/ μs
Electrostatic Discharge Protection Level	Human Body Model per JESD22-A114	ESD	2000		V
	Charged Device Model per JESD22-C101		500		
Junction Temperature		T_J	-40	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-65	+150	$^\circ\text{C}$
Lead Soldering Temperature, 10 Seconds		T_L		+260	$^\circ\text{C}$

Note(1): Lesser of 6.5V or $V_I + 0.3\text{V}$.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Prisemi does not recommend exceeding them or designing to absolute maximum ratings.

Parameter		Symbol	Min.	Max.	Units
Supply Voltage		V_{BUS}	4.5	5.75	V
Maximum Battery Voltage when Boost enabled		$V_{BAT(MAX)}$		4.5	V
Negative VBUS Slew Rate during VBUS Short Circuit, $C_{MID} \leq 22\mu\text{F}$, see VBUS Short While Charging	$T_A \leq 60^\circ\text{C}$	$-\frac{dV_{BUS}}{dt}$		4	V/ μs
	$T_A \geq 60^\circ\text{C}$			2	
Ambient Temperature		T_A	-30	+85	$^\circ\text{C}$
Junction Temperature (see Thermal Protection section)		T_J	-30	+140	$^\circ\text{C}$

Thermal Properties

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature $T_{J(max)}$ at a given ambient temperature T_A .

Parameter	Symbol	Typical	Units
Junction-to-Ambient Thermal Resistance	θ_{JA}	60	$^{\circ}C/W$
Junction-to-PCB Thermal Resistance	θ_{JB}	20	$^{\circ}C/W$

Electrical characteristics per line@25°C (unless otherwise specified)

Unless otherwise specified: according to the circuit of Figure 1; recommended operating temperature range for T_J and T_A ; $V_{BUS}=5.0V$; HZ_MODE; OPA_MODE=0; (Charge Mode); SCL, SDA, OTG=0 or 1.8V; and typical values are for $T_J=25^{\circ}C$.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Power Supplies						
VBUS Current	I_{VBUS}	$V_{BUS} > V_{BUS(MIN)}$, PWM Switching		1.5	10	mA
		$V_{BUS} > V_{BUS(MIN)}$; PWM Enabled, Not Switching (Battery OVP Condition); I_IN Setting=100mA		1.2	10	mA
VBAT to VBUS Leakage Current	I_{LKG}	$0^{\circ}C < T_J < 85^{\circ}C$ $V_{BAT}=4.2V, V_{BUS}=0V$		0.2	1	μA
Battery Discharge Current in High-Impedance Mode	I_{BAT}	$0^{\circ}C < T_J < 85^{\circ}C$ $V_{BAT}=4.2V$		5	10	μA
Charger Voltage Regulation						
Charge Voltage Range	V_{OREG}		4.1		4.40	V
Charge Voltage Accuracy		$T_J = 25^{\circ}C$	-0.5%		+0.5%	
		$T_J = 0 \sim 125^{\circ}C$	-1%		1%	
Charging Current Regulation						
Output Charge Current Range	I_{OCHRG}	$V_{LOWV} < V_{BAT} < V_{OREG}$ $V_{BUS} > V_{SLP}, R_{SENSE}=50m\Omega^{(1)}$	656		1966	mA
Charge Current Accuracy Across R_{SENSE}		$T_J < 85^{\circ}C, V_{BAT}=3.8V$	92.5	100	107.5	%

Note(1): Maximum charge current can be set up to 2.25A by choosing lower resistor.

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Logic Levels: DISABLE, SDA, SCL, OTG						
High-Level Input Voltage	V_{IH}		1.2			V
Low-Level Input Voltage	V_{IL}				0.4	V
Input Bias Current	I_{IN}	Input Tied to GND or V_{IN}		0.01	1.00	μ A
Charge Termination Detection						
Termination Current Range	$I_{(TERM)}$	$V_{BAT} > V_{OREG} - V_{RCH}$ $V_{BUS} > V_{SLP}$	69		230	mA
Wake-up voltage						
Wake-up voltage Range	V_{wakeup}	Soft start current if vbat is lower than V_{wakeup} ($R_{sense}=56m\Omega$)	3.0	3.15	3.3	V
Wake-up current	I_{wakeup}			350		mA
Input Power Source Detection						
VBUS Input Voltage Rising	$V_{IN(MIN)1}$	To Initiate and Pass VBUS		4.29	4.42	V
Minimum VBUS during Charge	$V_{IN(MIN)2}$	During Charging		4.1	4.15	V
VBUS Validation Time	t_{VBUS_VALID}			25		ms
Special Charger (V_{BUS})						
Special Charger Setpoint	V_{SP}	$VSP[2:0]=100$		4.52		V
Special Charger Setpoint Accuracy			-3		+3	%
Input Current Limit						
Input Current Limit Threshold	I_{INLIM}	I_{IN} Set to 500mA		480		mA

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Battery Recharge Threshold						
Recharge Threshold	V_{RCH}	Below $V_{(OREG)}$		140	200	mV
STAT Output						
STAT Output Low	$V_{STAT(OL)}$	$I_{STAT}=10mA$			0.4	V
STAT High Leakage Current	$I_{STAT(OH)}$	$V_{STAT}=5V$			1	μA
Sleep Comparator						
Sleep-Mode Entry Threshold, $V_{BUS} - V_{BAT}$	V_{SLP}	V_{BUS} Falling		0.25		V
Power Switches (see Figure 2)						
Q3 On Resistance (VBUS to PMID)	$R_{DS(ON)}$	$I_{IN(LIMIT)}=500mA$		30	55	m Ω
Q1 On Resistance (PMID to SW)				45	70	
Q2 On Resistance (SW to GND)				55	75	
Charger PWM Modulator						
Oscillator Frequency	f_{SW1}		1.25	1.5	1.65	MHz
	f_{SW2}		1.65	2.0	2.3	
Maximum Duty Cycle	D_{MAX}				97	%
Minimum Duty Cycle	D_{MIN}			0		%
Boost Mode Operation (OPA_MODE=1, HZ_MODE=0)						
Boost Output Voltage at VBUS	V_{BOOST}	$3.3V < V_{BAT} < 4.5V$, I_{LOAD} from 0 to 500mA	4.75	5.05	5.3	V
Boost Mode Quiescent Current	$I_{BAT(BOOST)}$	PFM Mode, $V_{BAT}=3.6V$, $I_{OUT}=0$		1.6	10	mA
Minimum Battery Voltage for Boost Operation	$UVLO_{BST}$			3.0		V

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
VBUS Load Resistance						
VBUS to PGND Resistance	R_{VBUS}	Normal Operation		1500		K Ω
Protection and Timers						
VBUS Over-Voltage Shutdown	$V_{BUS_{OVP}}$	V_{BUS} Rising	5.75	5.9	6.05	V
Hysteresis		V_{BUS} Falling		150		mV
Battery Short-Circuit Threshold	V_{SHORT}	V_{BAT} Rising	1.9	2.0	2.1	V
Hysteresis		V_{BAT} Falling		0.1		
Linear Charging Current	I_{SHORT}	$V_{BAT} < V_{SHORT}$	20	30	40	mA
Thermal Shutdown Threshold ⁽²⁾	$T_{SHUTDWN}$	T_J Rising		145		$^{\circ}\text{C}$
Hysteresis ⁽²⁾		T_J Falling		10		
12H timer	t_{12H}	Charger Enabled		12		hour
90-Minute Timer	T_{90MIN}	90-Minute Mode		90		min
32-Second Timer	T_{32s}	32-second Mode		32		Sec

Notes(2): Guaranteed by design; not tested in production.

I²C Timing Specifications

Guaranteed by design.

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
SCL Clock Frequency	f _{SCL}	Standard Mode			100	kHz
		Fast Mode			400	
Bus-Free Time between STOP and START Conditions	t _{BUF}	Standard Mode		4.7		μs
		Fast Mode		1.3		

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
START or Repeated START Hold Time	t _{HD;STA}	Standard Mode		4		μs
		Fast Mode		600		ns
SCL LOW Period	t _{LOW}	Standard Mode		4.7		μs
		Fast Mode		1.3		
SCL HIGH Period	t _{HIGH}	Standard Mode		4		μs
		Fast Mode		600		ns
Repeated START Setup Time	t _{SU;STA}	Standard Mode		4.7		μs
		Fast Mode		600		ns
Data Setup Time	t _{SU;DAT}	Standard Mode		250		ns
		Fast Mode		100		
Data Hold Time	t _{HD;DAT}	Standard Mode	0		3.45	μs
		Fast Mode	0		900	ns
SCL Rise Time	t _{RCL}	Standard Mode	20+0.1C _B		1000	ns
		Fast Mode	20+0.1C _B		300	
SCL Fall Time	t _{FCL}	Standard Mode	20+0.1C _B		300	ns
		Fast Mode	20+0.1C _B		300	
SDA Rise Time Rise Time of SCL after a Repeated START Condition and after ACK Bit	t _{RDA} t _{RCL1}	Standard Mode	20+0.1C _B		1000	ns
		Fast Mode	20+0.1C _B		300	

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
SDA Fall Time	t_{FDA}	Standard Mode	20+0.1C _B		300	ns
		Fast Mode	20+0.1C _B		300	
Stop Condition Setup Time	$t_{SU,STO}$	Standard Mode		4		μs
		Fast Mode		600		ns
Capacitive Load for SDA, SCL	C _B				400	pF

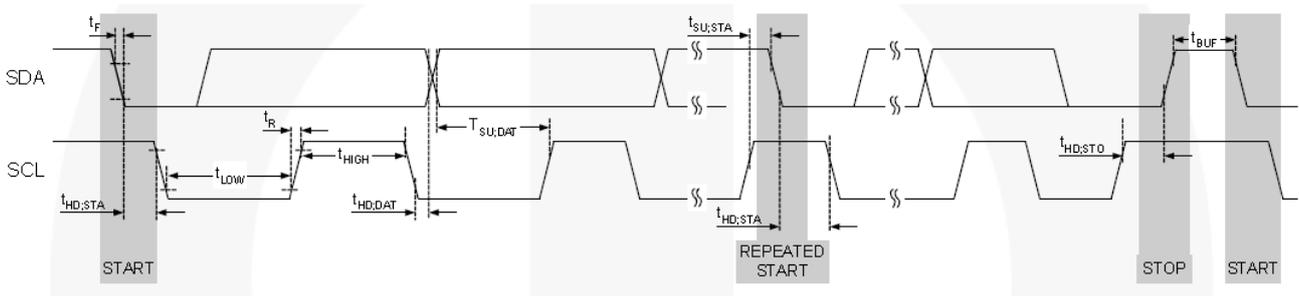


Figure 4. I²C Interface Timing for Fast and Slow Modes

Charge Mode Typical Characteristics

Unless otherwise specified, circuit of Figure 1, $V_{OREG}=4.35V$, $V_{BUS}=5.0V$, and $T_A=25^\circ C$.

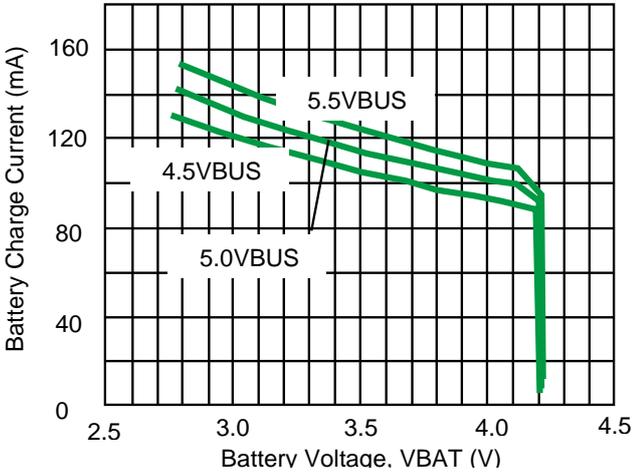


Figure 5. Battery Charge Current vs. V_{BUS} with $I_{INLIM}=100mA$

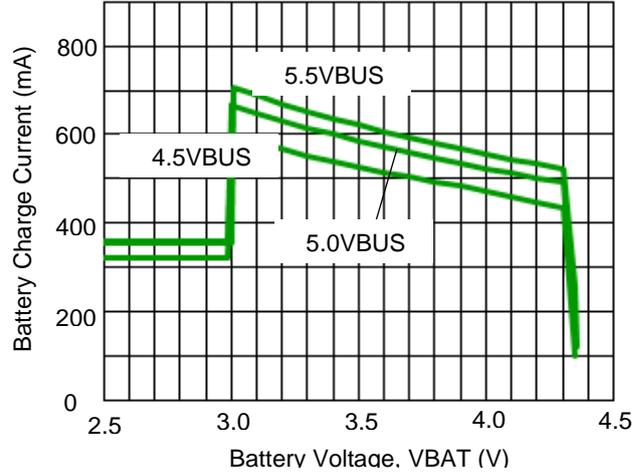


Figure 6. Battery Charge Current vs. V_{BUS} with $I_{INLIM}=500mA$

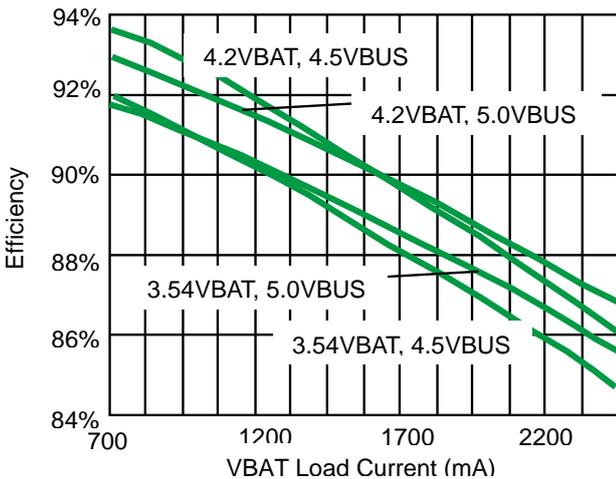


Figure 7. Charger Efficiency, No I_{INLIM} , $I_{CHARGE}=2253mA$

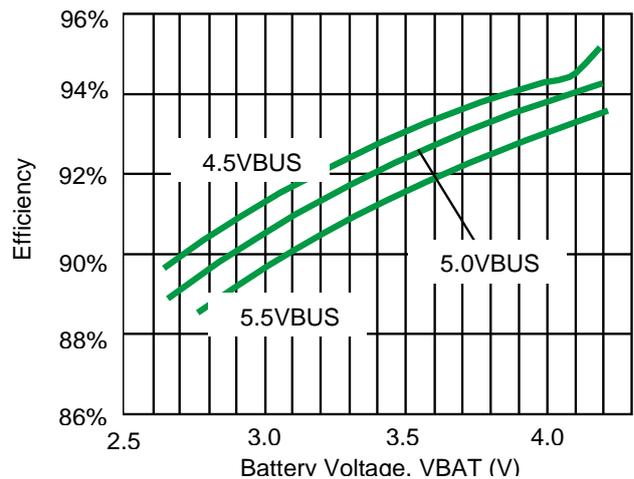


Figure 8. Charger Efficiency vs. V_{BUS} , $I_{INLIM}=500mA$



Figure 9. Auto-Charge Startup at V_{BUS} Plug-in, $I_{INLIM}=100mA$, $V_{BAT}=3.9V$



Figure 10. Auto-Charge Startup at V_{BUS} Plug-in, $I_{INLIM}=500mA$, $V_{BAT}=3.9V$



Figure 11. Auto-Charge Startup with 300mA Limited Charger/Adaptor, $I_{INLIM}=500mA$, $V_{BAT}=3.9V$



Figure 12. Charger Startup with HZ_MODE Bit Reset, $I_{INLIM}=500mA$, $I_{OCHARGE}=956mA$, $O_{REG}=4.2V$, $V_{BAT}=3.6V$



Figure 13. Battery Removal / Insertion during Charging, $V_{BAT}=3.9V$, $I_{OCHARGE}=956mA$, No I_{INLIM} , $TE=0$

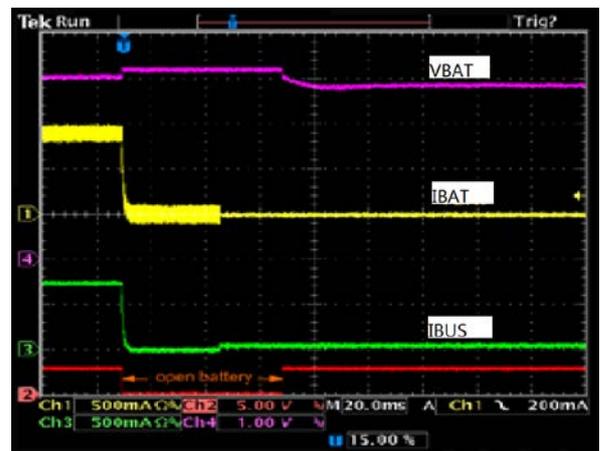


Figure 14. Battery Removal / Insertion during Charging, $V_{BAT}=3.9V$, $I_{OCHARGE}=956mA$, No I_{INLIM} , $TE=1$



Figure 15. No Battery at V_{BUS} Power-up

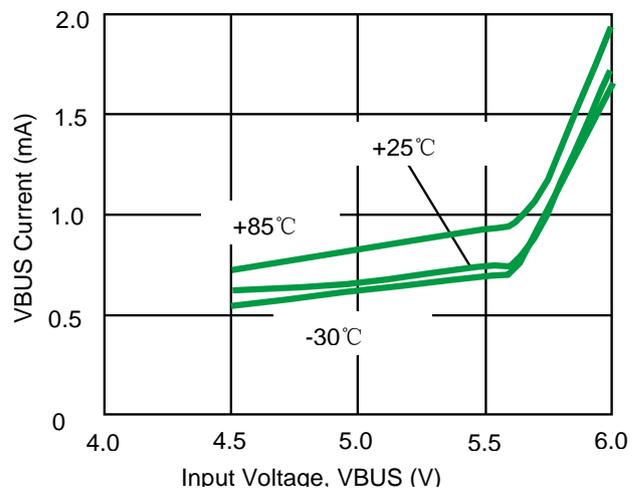


Figure 16. VBUS Current with Battery Open

Boost Mode Typical Characteristics

Unless otherwise specified, using circuit of Figure 1, $V_{BAT}=3.6V$, $T_A=25^\circ C$.

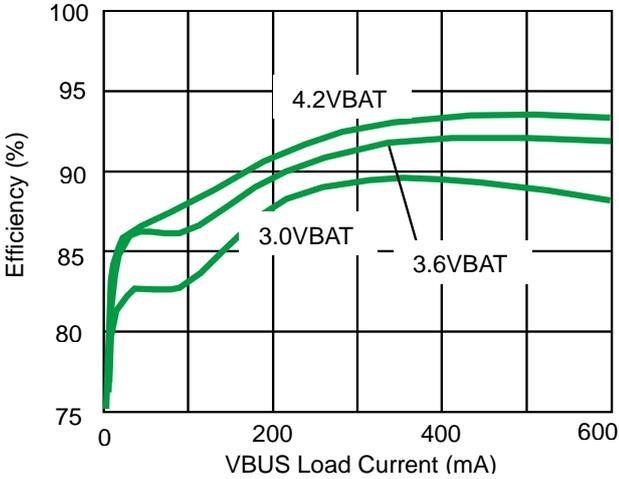


Figure 17. Efficiency vs. VBAT

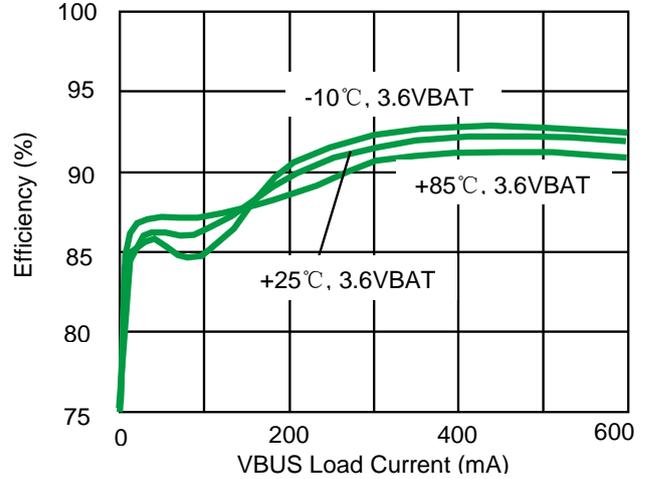


Figure 18. Efficiency Over Temperature

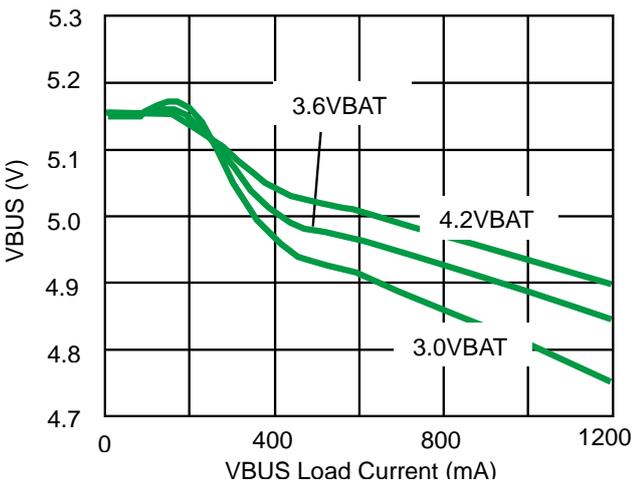


Figure 19. Output Regulation vs. VBAT

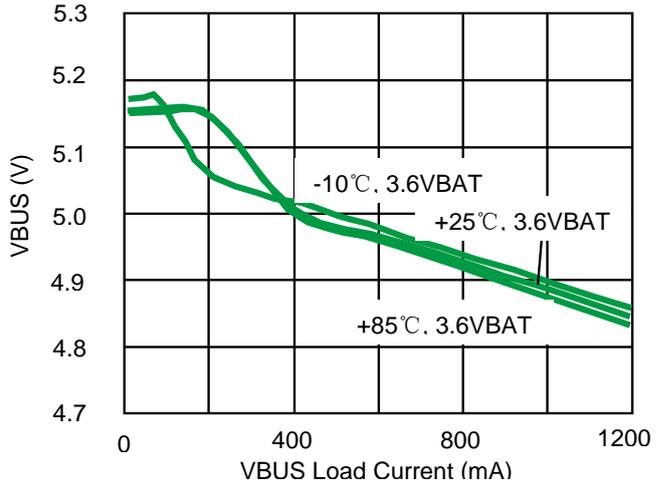


Figure 20. Output Regulation Over Temperature

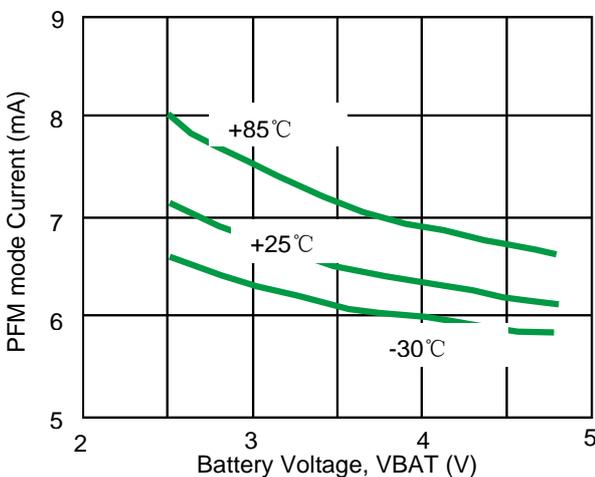


Figure 21. PFM mode Current

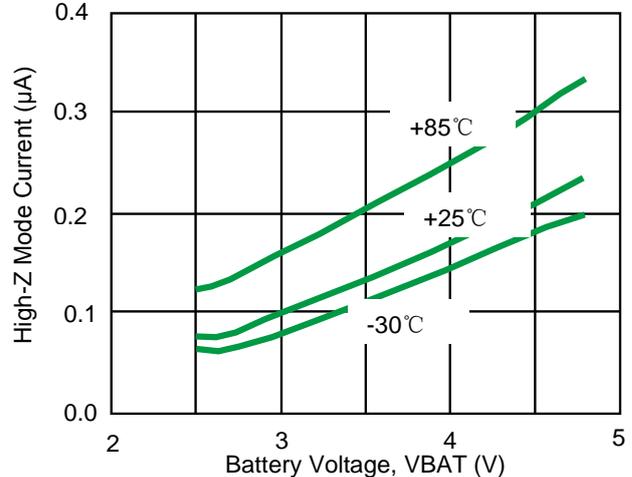


Figure 22. High-Impedance Mode Battery Current
HZ_MODE=1

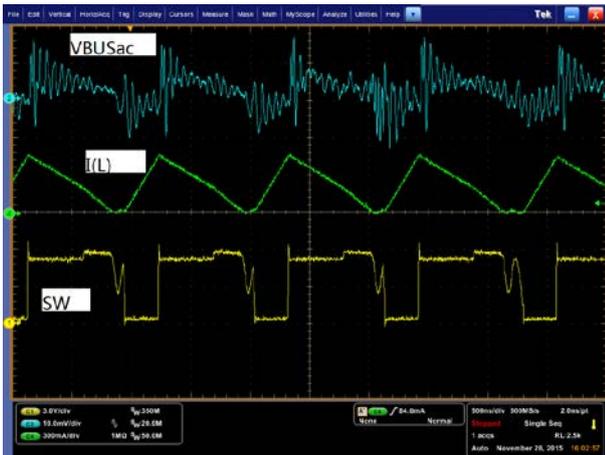


Figure 23. Boost PWM Waveform



Figure 24. Boost PFM Waveform

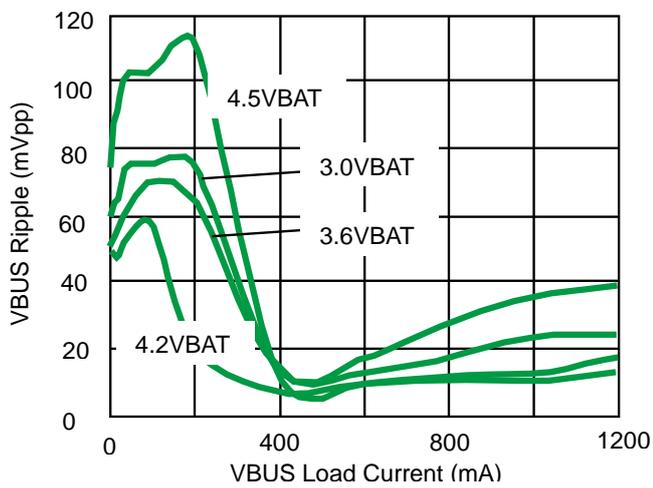


Figure 25. Output Ripple vs. VBAT

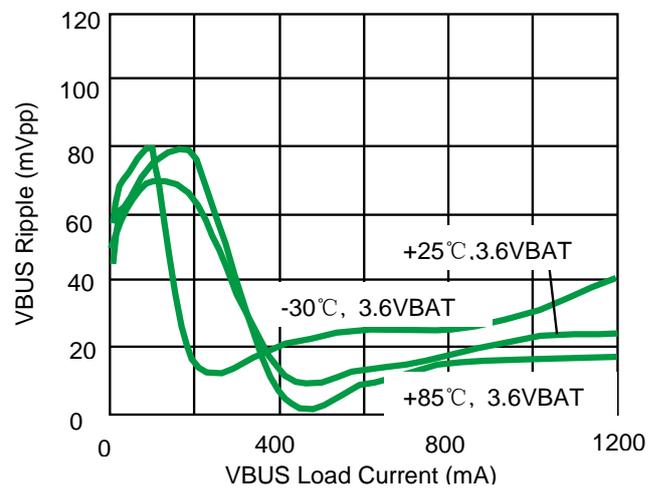


Figure 26. Output Ripple vs. Temperature



Figure 27. Startup, 3.6VBAT, 44Ω Load, Additional 10μF, X5R Across VBUS

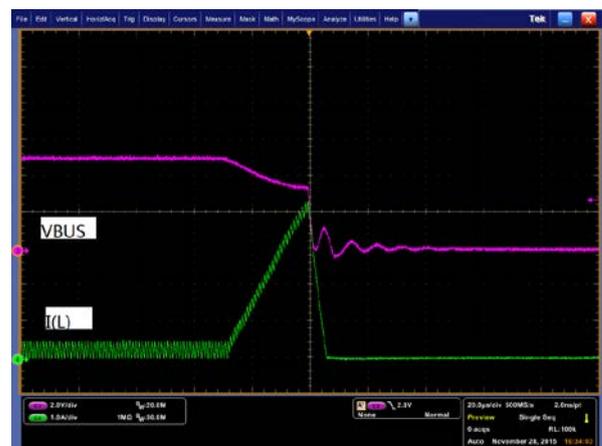


Figure 28. VBUS Fault Response, 3.6VBAT

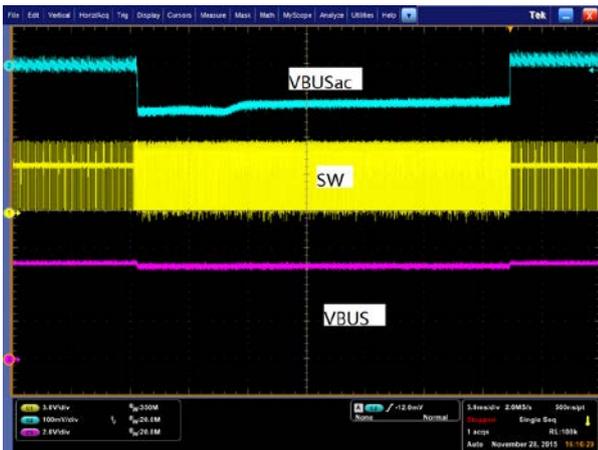


Figure 29. Load Transient, 1-150-1mA, $t_R=t_F=100ns$

Circuit Description/ Overview

When charging batteries with a current-limited input source, such as USB, a switching charger’s high efficiency over a wide range of output voltages minimizes charging time.

PSC5425E combines a highly integrated synchronous buck regulator for charging with a synchronous boost regulator, which can supply 5V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

The PSC5425E has three operating modes:

1. Charge Mode (VBUS is valid.):

Charge a single-cell Li-ion or Li-polymer battery.

2. Boost Mode:

Provide 5V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.

3. Standby mode (VBUS is not valid.)

Current flow from VBUS to the battery or from the battery to VBUS is blocked.

1) If HZ_MODE=0, boost can be turned on thru I2C.

2) If HZ_MODE=1, boost is always off.

Note: Default settings are denoted by bold typeface.

Charge Mode

In Charge Mode, PSC5425E employs four regulation loops:

1. Input Current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I²C interface.

2. Charging Current: Limits the maximum charging current. This current is sensed using an external R_{SENSE} resistor.

3. Charge Voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage rises, the battery’s internal impedance and R_{SENSE} work in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the charging current drops below the I_{TERM} threshold.

4. Input Voltage: PSC5425E employ an additional loop to limit the amount of drop on VBUS to a programmable voltage (V_{SP}) to accommodate “special chargers” that limit current to a lower current than might be available from a “normal” USB wall charger.

Battery Charging Curve

If the battery voltage is below V_{SHORT} , a linear current source pre-charges the battery until V_{BAT} reaches V_{SHORT} . The PWM charging circuit is then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The PSC5425E is designed to work with a current-limited input source at V_{BUS} . During the current regulation phase of charging, I_{INLIM} or the programmed charging current limits the amount of current available to charge the battery and power the system. The effect of I_{INLIM} on I_{CHARGE} can be seen in Figure 31.

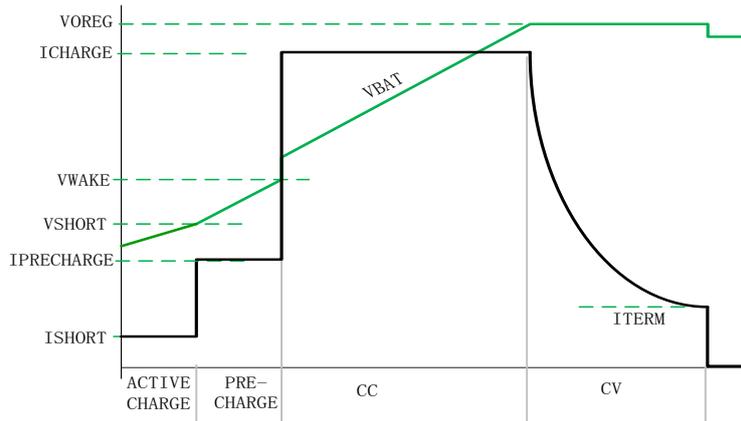


Figure 30. Charge Curve, I_{CHARGE} Not Limited by I_{INLIM}

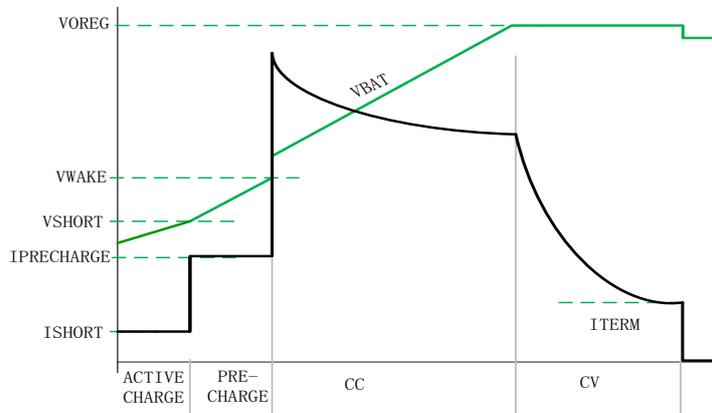


Figure 31. Charge Curve, I_{INLIM} Limits I_{CHARGE}

USB-Compliant Single-Cell Li-Ion Switching Charger with USB-OTG Boost Regulator

Assuming that V_{OREG} is programmed to the cell's fully charged "float" voltage, the current that the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to V_{OREG} declines, and the charger enters the voltage regulation phase of charging. When the current declines to the programmed I_{TERM} value, the charge cycle is complete. Charge current termination can be disabled by resetting the TE bit (REG1[3]).

The charger output or "float" voltage can be programmed by the OREG bits from 4.2V to 4.4V as shown in Table 1.

Table 1. OREG Bits (OREG[7:2]) vs. Charger V_{OUT} (V_{OREG}) Float Voltage

Decimal	Hex	VOREG
0-1	00-01	4.1
2-35	02-23	4.20
36-44	24-2C	4.35
45-62	2D-3E	4.40

The following charging parameters can be programmed by the host through I²C:

Table 2. Programmable Charging Parameters

Parameter	Name	Register
Output Voltage Regulation	V_{OREG}	REG2[7:2]
Battery Charging Current Limit	I_{OCHRG}	REG4[6:4]
Input Current Limit	I_{INLIM}	REG1[7:6]
Charge Termination Limit	I_{TERM}	REG4[2:0]
Weak Battery Voltage	V_{LOWV}	Reserved.

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below $V_{OREG} - V_{RCH}$

Charge Current Limit (I_{CHARGE}) & Termination Current Limit
Table 3. IOCHARGE (REG4 [6:4]) Current as Function of IOCHARGE Bits and RSENSE Resistor Values

DEC	BIN	HEX	$V_{\text{RSENSE}}(\text{mV})$	$I_{\text{CHARGE}}(\text{mA})$	
				56m Ω	50m Ω
0	000	00	32.8	586	656
1	001	01	39.3	702	786
2	010	02	52.4	936	1048
3	011	03	59.0	1054	1180
4	100	04	72.1	1288	1442
5	101	05	78.7	1405	1574
6	110	06	91.8	1639	1836
7	111	07	98.3	1755	1966

Table 4. Terminated (REG4 [2:0]) Current as Function of ITERM Bits and RSENSE Resistor Values

DEC	BIN	HEX	$V_{\text{RSENSE}}(\text{mV})$	$I_{\text{TERM}}(\text{mA})$	
				56m Ω	50m Ω
0	000	00	2.5	45	50
1	001	01	3.8	68	76
2	010	02	5.0	89	100
3	011	03	6.3	113	126
4	100	04	7.5	134	150
5	101	05	8.8	157	176
6	110	06	10.0	179	200
7	111	07	11.3	202	226

Current charge termination is enabled when TE (REG1[3])=1. When charging current falls below I_{TERM} , PWM charging stops. If the charging source is still connected, STAT changes to CHARGE DONE (10).

PWM Controller in Charge Mode

The IC uses a current-mode PWM controller to regulate the output voltage and battery charge currents.

Safety Timer

The charger has a time out function for wake-up charge and normal charge. For wake-up charge the internal timer is set to typically 90 minutes. After 90 minutes of charging, if Vbat is still lower than 3.1V (typical), the charger is turned OFF and will not resume operation.

For normal charging the timer is set to 12 hours.

If the charger is still operating after typical 12 hours it will be turned OFF and will resume operating only if the condition (VOREG-VBAT) >100mV is met.

The 90-min and 12-hour timer can be reset by plugging out/in the adapter.

PSC5425E also has a 32s-timer for watch-dog function which is only for OTG mode. If it does not receive any read/write command during 32s, it will be reset to default parameters and quit OTG mode.

VBUS POR / Non-Compliant Charger Rejection

When VBUS is inserted, VBUS must remain above $V_{IN(MIN)1}$ and below $V_{BUS_{OVP}}$ for t_{VBUS_VALID} (25ms) before the IC initiates charging. The VBUS validation sequence always occurs before charging is initiated or re-initiated (for example, after a VBUS OVP fault or a V_{RCH} recharge initiation).

t_{VBUS_VALID} ensures that unfiltered 50/60Hz chargers and other non-compliant chargers are rejected.

Input Current Limiting

To minimize charging time without overloading VBUS current limitations, the IC's input current limit can be programmed by the I_{INLIM} bits (REG1[7:6]).

Table 5. Input Current Limit

I_{INLIM} REG1[7:6]	Input Current Limit
00	150mA
01	500mA
10	800mA
11	No Limit

Special Charger

The PSC5425E have additional functionality to limit input current in case a current-limited “special charger” is supplying VBUS. The PSC5425E slowly increases the charging current until either:

I_{INLIM} or $I_{OCHARGE}$ is reached or $V_{BUS}=V_{SP}$

If V_{BUS} collapses to V_{SP} when the current is ramping up, the PSC5425E charge with an input current that keeps $V_{BUS}=V_{SP}$.

Table 6. Input Voltage Limit

V_{SP} REG5[2:0]	Input Voltage Limit (V)
000	4.214
001	4.29
010	4.366
011	4.442
100	4.52(Default)
101	4.59
110	4.67
111	4.8

Thermal Protection

If the temperature increases beyond $T_{SHUTDOWN}$; charging is suspended.

Additional θ_{JA} data points, measured using the PSC5425E evaluation board, are given in Table 11 (measured with $T_A=25^{\circ}C$).

Note that as power dissipation increases, the effective θ_{JA} decreases due to the larger difference between the die temperature and its ambient.

Charge Mode Input Supply Protection

Input Supply Low-Voltage Detection

The IC continuously monitors VBUS during charging. If V_{BUS} falls below $V_{IN(MIN)}$, the IC terminates charging.

Input Over-Voltage Detection

When the VBUS exceeds $V_{BUS_{OVP}}$, the IC suspends charging

When VBUS falls about 150mV below $V_{BUS_{OVP}}$, the fault is cleared and charging resumes after VBUS is revalidated (see *VBUS POR / Non-Compliant Charger Rejection*).

Charge Mode Battery Detection & Protection

VBAT Over-Voltage Protection

The OREG voltage regulation loop prevents VBAT from overshooting the OREG voltage by more than 50mV when the battery is removed. When the PWM charger runs with no battery, the TE bit is not set and a battery is inserted that is charged to a voltage higher than V_{OREG} ; PWM pulses stop.

System Operation with No Battery

The PSC5425E continue charging after V_{BUS} POR with the default parameters, regulating the V_{BAT} line to 4.2V until the host processor issues commands. In this way, the PSC5425E can start the system without a battery.

Using following sequence is suggested:

1. When VBUS is plugged in, I_{INLIM} is set to 500mA until the system processor powers up and can set parameters through I²C.
2. Program the Safety Register.
3. Set I_{INLIM} to 11 (no limit).
4. Set OREG to the desired value (typically 4.2V).
5. Set I_{INLIM} to 500mA if a USB source is connected.

During the initial system startup, while the charger IC is being programmed, the system current is limited to 500mA before

Charger Status

The STAT pin is for test purpose, the IC provides the charging status in REG0[5:4].

Operational Mode Control

OPA_MODE (REG1[0]) and the HZ_MODE (REG1[1]) bits in conjunction with the DISABLE pin define the operational mode of the charger.

Table 7. Operation Mode Control

HZ_MODE	OPA_MODE	DISABLE	Operation Mode
X	0	0	Charge
X	X	1	Charger disabled
0	1	X	Boost
1	X	X	High Impedance

The IC resets the OPA_MODE bit whenever the boost is deactivated, whether due to a fault or being disabled by setting the HZ_MODE bit. Setting HZ_MODE=1 through I²C won't disable charger but only disable boost function.

Boost PWM Control

The IC uses a minimum on-time and computed minimum off-time to regulate V_{BUS}. The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During PWM Mode, the output voltage drops slightly as the input current rises. With a constant V_{BAT}, this appears as a constant output resistance.

PFM Mode

If V_{BUS} > V_{REFBOOST} (nominally 5.15V) when the minimum off-time has ended, the regulator enters PFM Mode. Boost pulses are inhibited until V_{BUS} < V_{REFBOOST}. The minimum on-time is increased to enable the output to pump up sufficiently with each PFM boost pulse. Therefore the regulator behaves like a constant on-time regulator, with the bottom of its output voltage ripple at 5.15V in PFM Mode.

Startup

When the boost regulator is shut down, current flow is prevented from V_{BAT} to V_{BUS}, as well as reverse flow from V_{BUS} to V_{BAT}.

SS State

This IC has built-in soft start function to prevent the IC being out of control. The reference voltage is slightly raised to the normal voltage within about 50us. In SS state, peak current is limited as 1.5x of that in normal condition. When SS is done, the current limit is set to 100%.

BST State

This is the normal operating mode of the regulator. The regulator uses a minimum t_{OFF}-minimum t_{ON} modulation scheme. The minimum t_{OFF} is proportional to $\frac{V_{IN}}{V_{OUT}}$ Which keeps the regulator's switching frequency reasonably constant in CCM. t_{ON(MIN)} is proportional to V_{BAT} and is a higher value if the inductor current reached 0 before t_{OFF(MIN)} in the prior cycle. To ensure the V_{BUS} does not pump significantly above the regulation point, the boost switch remains off as long as FB > V_{REF}.

Boost Faults

If a BOOST fault occurs:

1. The STAT pin pulses.
2. OPA_MODE bit is reset.
3. The power stage is in High-Impedance Mode.

I²C Interface

The PSC5425E's serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Mode I²C-Bus® specifications. The PSC5425E's SCL line is an input and its SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and when signaling ACK. All data is shifted in MSB (bit 7) first.

Slave Address

Table 8. I²C Slave Address Byte

Part Types	7	6	5	4	3	2	1	0
PSC5425E	1	1	0	1	0	1	0	R/ \overline{W}

In hex notation, the slave address assumes a 0 LSB. The hex slave address for the PSC5425E is D4H.

Bus Timing

As shown in Figure 32, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

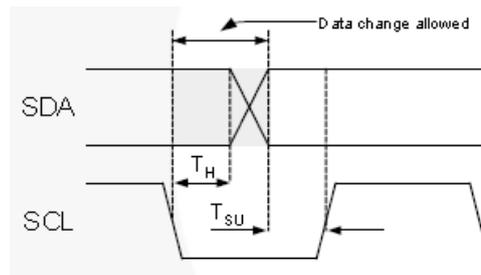


Figure 32. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCL HIGH. A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH, as shown in Figure 33.

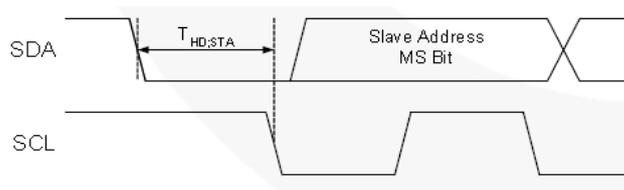


Figure 33. Start Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 34.

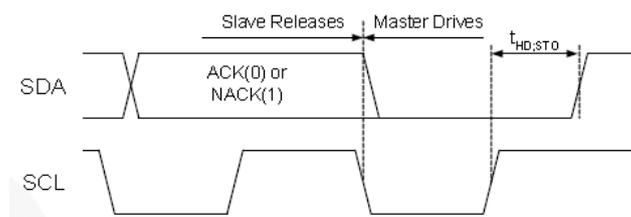


Figure 34. Stop Bit

During a read from the PSC5425E (Figure 35), the master issues a Repeated Start after sending the register address and before resending the slave address. The Repeated Start is a 1-to-0 transition on SDA while SCL is HIGH, as shown in Figure 35.

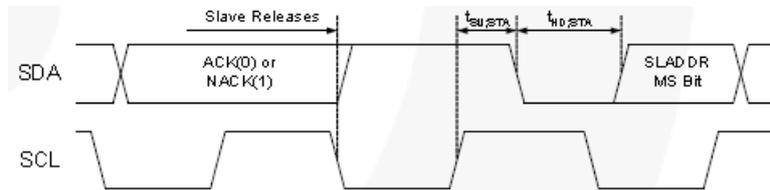


Figure 35. Repeated Start Timing

Read and Write Transactions

The figures below outline the sequences for data read and write. Bus control is signified by the shading of the packet, defined as

Master Drives Bus

and

Slave Drives Bus

All addresses and data are MSB first.

Table 9. Bit Definitions for Figure 36, Figure 37

Symbol	Definition
S	START, see Figure 33
A	ACK. The slave drives SDA to 0 to acknowledge the preceding packet.
\bar{A}	NACK. The slave sends a 1 to NACK the preceding packet.
R	Repeated START, see Figure 35
P	STOP, see Figure 34



Figure 36. Write Transaction



Figure 37. Read Transaction

Register Descriptions
Table 10. I²C Register Address

IC	Register		Address Bits							
	Name	REG#	7	6	5	4	3	2	1	0
PSC5425E	CONTROL0	0	0	0	0	0	0	0	0	0
	CONTROL1	1	0	0	0	0	0	0	0	1
	OREG	2	0	0	0	0	0	0	1	0
	IC_INFO	3	0	0	0	0	0	0	1	1
	IBAT	4	0	0	0	0	0	1	0	0
	SP_CHARGER	5	0	0	0	0	0	1	0	1
	SAFETY	6	0	0	0	0	0	1	1	0
	SPR	51	1	0	0	1	0	0	0	1
	TEST	10	0	0	0	1	0	0	0	0

Table 11. Register Bit Definitions

This table defines the operation of each register bit for all IC versions. Default values are in bold text.

Bit	Name	Value	Type	Description
CONTROL0		Register Address:00		Default Value=X1XX 0XXX
7:6	-	-	-	Reserved [1]
5:4	STAT	00	R	Ready
		01	R	Charge in progress
		10	R	Charge done
		11	-	Reserved
3	BOOST	0	R	IC is not in Boost Mode
		1	R	IC is in Boost Mode
2:0	-	-	-	Reserved

Bit	Name	Value	Type	Description	
CONTROL1 Register Address:01 Default Value=0111 0000					
7:6	I _{INLIM}		R/W	Input current limit, see Table 5	
				REG01[7:6] BIN	Input Current Limit
				00	150mA
				01	500mA
				10	800mA
5:4	V _{LOWV}		R/W	Reserved.	
3	TE	0	R/W	Disable charge current termination	
		1		Enable charge current termination	
2	$\overline{\text{CE}}$	0	R/W	Enable charge;	
		1		Disable charge;	
1	HZ_MODE	0	R/W	Not High-Impedance Mode	
		1		High-Impedance Mode	
0	OPA_MODE	0	R/W	Charge Mode	
		1		Boost Mode	
OREG Register Address:02 Default Value=0000 0000					
7:2	OREG		R/W	Charger output “float” voltage; programmable from 4.1 to 4.4V increments; defaults to 000000 (4.1V) , see Table 1	
				REG02[7:2] BIN	VOREG
				000000 - 000001	4.1V
				000010 - 100011	4.2V
				100100 - 101100	4.35V
101101 - 111110	4.4V				
1:0	-	0	R/W	-	
IC_INFO Register Address: 03 or 3B Default Value=1111 0XXX					
7:5	Vendor Code	111	R	Identifies Prisemi as the IC supplier	
4:0	TN	10	R	Product Tracking Number;	

Bit	Name	Value	Type	Description				
IBAT				Register Address: 04 Default Value=10001001				
7	RESET	1	W	Writing a 1 reset all charge parameters. Read returns 0				
6:4	IOCHARGE	Table 5	R/W	Programs the maximum charge current, see Table 3				
				REG51[0]	REG04[6:4] BIN	Vrsns(mV)	Icharge (mA)	
							56mΩ	50mΩ
				0	000	32.8	586	656
					001	39.3	702	786
					010	52.4	936	1048
					011	59	1054	1180
					100	72.1	1288	1442
					101	78.7	1405	1574
					110	91.8	1639	1836
					111	98.3	1755	1966
				1	000	26.7	477	534
					001	33.3	595	666
					010	40	714	800
					011	46.7	834	934
					100	53.3	952	1066
					101	60	1071	1200
					110	66.7	1191	1334
111	86.7	1548	1734					
3	-	-	R	Reserved.				
2:0	ITERM	Table 6	R/W	Programs the terminated charge-done current, see Table 4				
				REG04[2:0]	ITERM (mA)			
				BIN	Vrsns	56mΩ	50mΩ	
				000	2.5	45	50	
				001	3.8	68	76	
				010	5.0	89	100	
				011	6.3	113	126	
				100	7.5	134	150	
				101	8.8	157	176	
				110	10.0	179	200	
				111	11.3	202	226	

Bit	Name	Value	Type	Description	
SP_CHARGER Register Address: 05 Default Value=001X X100					
7	ADD20MV	0	R/W	The OREG value will be increased 20mv if bit7 is set "1"; For example, 4.2 will be 4.22V if set ADD20MV=1;	
6:5	Reserved	-	-	Reserved	
4	SP	0	R	Special charger is not active (V_{BUS} is able to stay above V_{SP})	
		1		Special charger has been detected and V_{BUS} is being regulated to	
3	EN_LEVEL	0	R/W	Reserved.	
2:0	VSP	100	R/W	Input voltage limit, see <i>Table 6</i>	
				REG05[2:0] BIN	VSP (V)
				000	4.214
				001	4.29
				010	4.366
				011	4.442
				100	4.52(default)
				101	4.59
				110	4.67
				111	4.8
SPR Register Address: 51 Default Value=0000 0000					
1	FSE	0	R/W	0: Choose PWM frequency 1.5Mhz; 1: Choose PWM frequency 2.0Mhz;	
0	ICE	0	R/W	Option for Charge current; see table 3;	
TEST Register Address: 10 Default Value=0000 0000					
2:0	TEST_STAT	000	R/W	000: STAT output is low if V_{BUS} is valid for charge, otherwise STAT is floating output; 111: STAT output is always floating;	

PCB Layout Considerations

1. To obtain optimal performance, the power input capacitors, connected from input to PGND, should be placed as close as possible to the pin. The output inductor should be placed close to the IC and the output capacitor connected between the inductor and PGND of the IC. The intent is to minimize the current path loop area from the SW pin through the LC filter and back to the PGND pin. To prevent high frequency oscillation problems, proper layout to minimize high frequency current path loop is critical. (See Figure 38.) The sense resistor should be adjacent to the junction of the inductor and output capacitor. Route the sense leads connected across the RSNS back to the IC, close to each other (minimize loop area) or on top of each other on adjacent layers (do not route the sense leads through a high-current path). (See Figure 39.)
2. Place all decoupling capacitors close to their respective IC pins and close to PGND (do not place components such that routing interrupts power stage currents). All small control signals should be routed away from the high current paths.
3. The PCB should have a ground plane (return) connected directly to the return of all components through vias (two vias per capacitor for power-stage capacitors, two vias for the IC PGND, one via per capacitor for small- signal components). A star ground design approach is typically used to keep circuit block currents isolated (high-power/low-power small-signal) which reduces noise-coupling and ground-bounce issues. A single ground plane for this design gives good results. With this small layout and a single ground plane, there is no ground-bounce issue, and having the components segregated minimizes coupling between signals.
4. The high-current charge paths into VBUS, PMID and from the SW pins must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces. The PGND pins should be connected to the ground plane to return current through the internal low-side FET.
5. Place $22\mu\text{F}$ input capacitor as close to PMID pin and PGND pin as possible to make high frequency current loop area as small as possible. Place $1\mu\text{F}$ input capacitor as close to VBUS pin and PGND pin as possible to make high frequency current loop area as small as possible (see Figure 40).

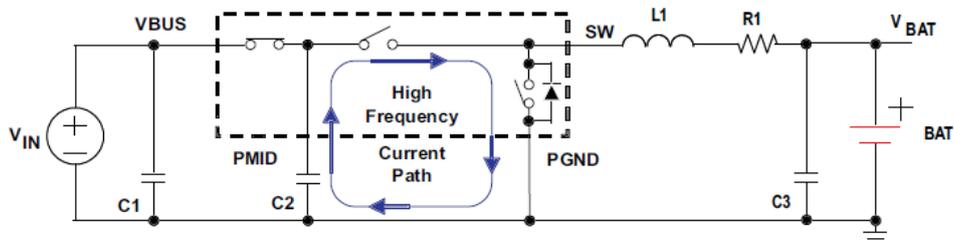


Figure 38. high frequency current path

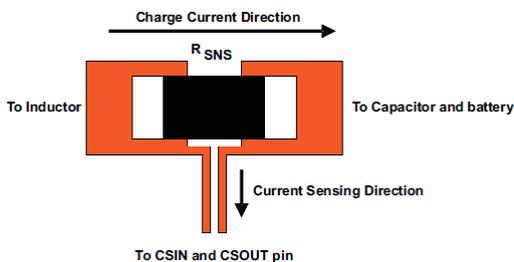


Figure 39. Sensing resistor PCB layout

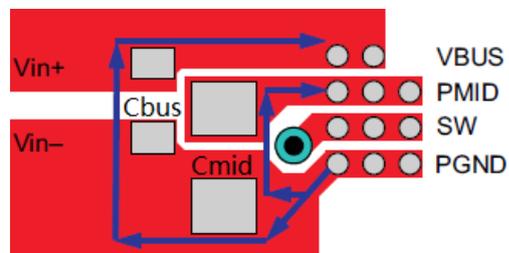
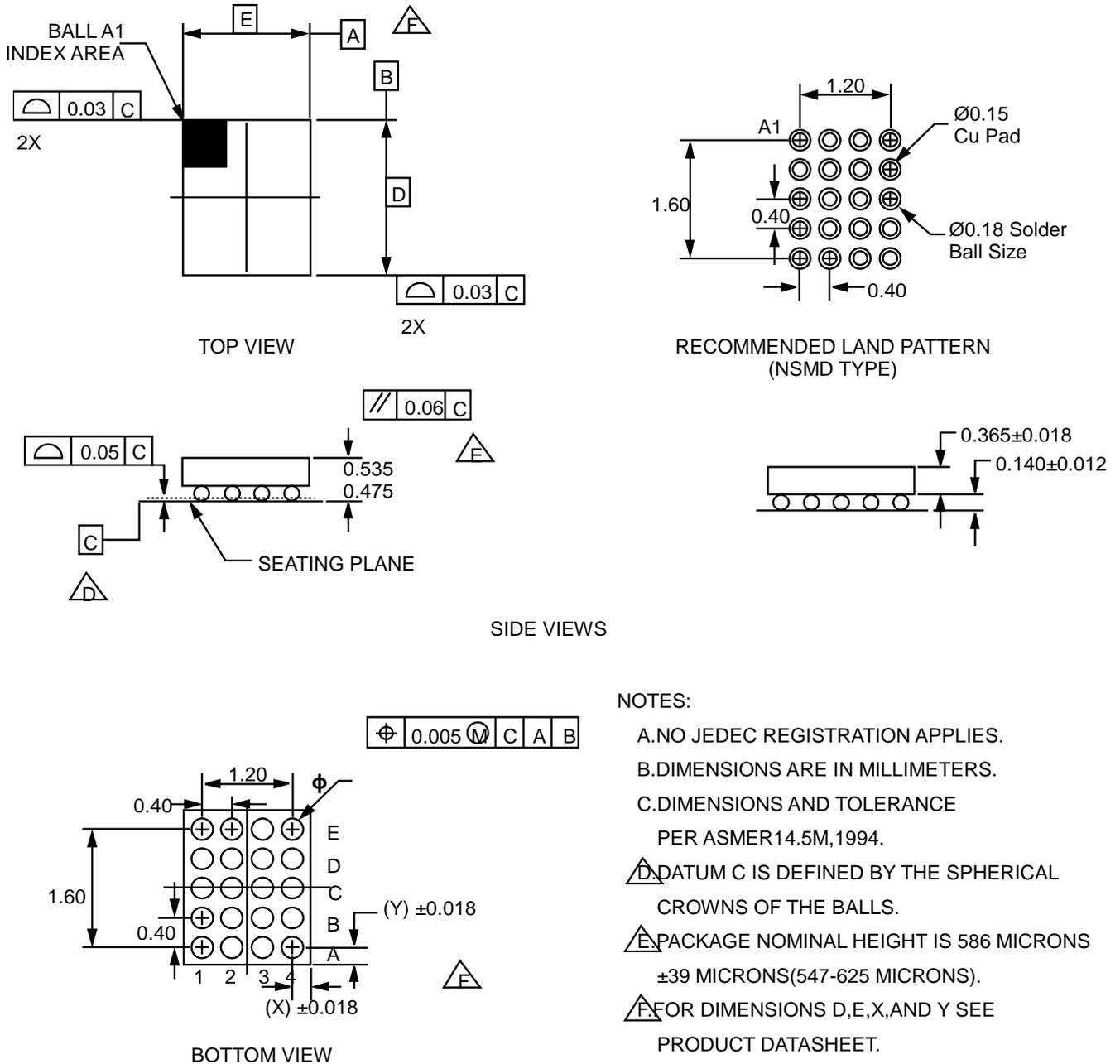


Figure 40. Input capacitor position and PCB layout example

Product dimension



NOTES:

- A.NO JEDEC REGISTRATION APPLIES.
- B.DIMENSIONS ARE IN MILLIMETERS.
- C.DIMENSIONS AND TOLERANCE PER ASMER14.5M,1994.
- D** DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E** PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS(547-625 MICRONS).
- F** FOR DIMENSIONS D,E,X,AND Y SEE PRODUCT DATASHEET.
- G.DRAWING FILNAME:MKT-UC020AArev2.

Figure 41. 20-Ball WLCSP, 4x5 Array, 0.4mm Pitch, 150µm Ball

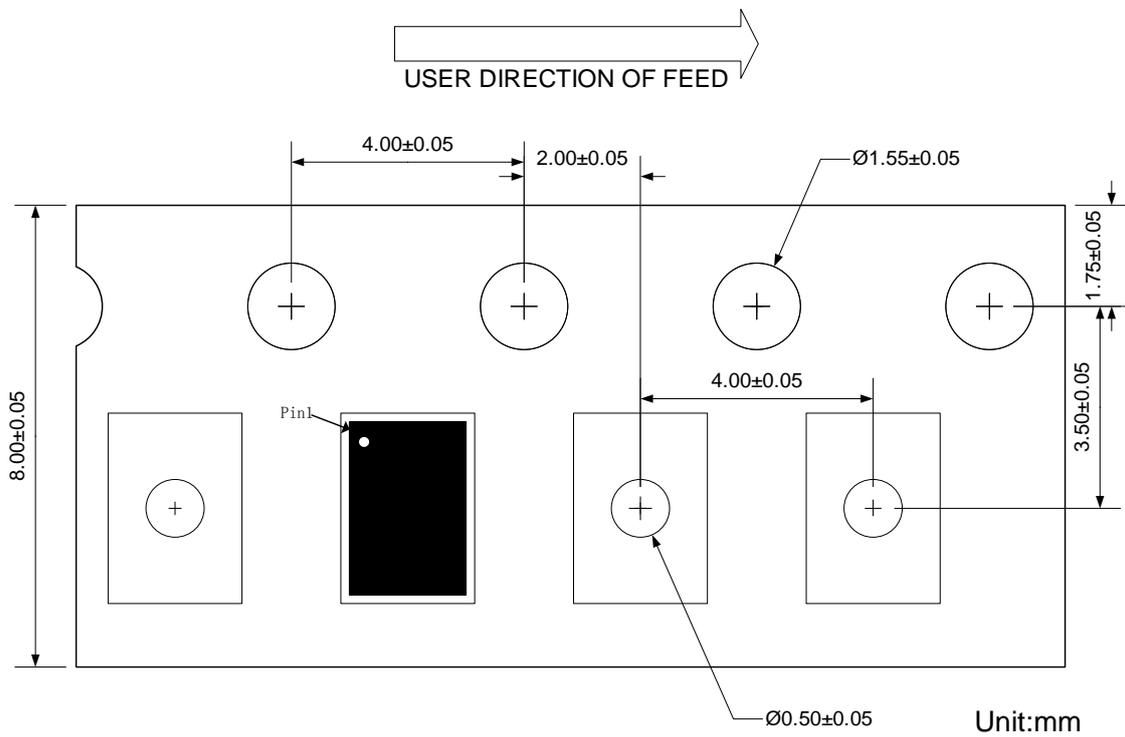
Product-Specific Dimensions (mm)

Product	D	E	X	Y	φ
PSC5425E	1.901±0.030	1.501±0.030	0.150	0.150	0.150±0.020

Ordering Information

Device	Package	Reel	Shipping
PSC5425E	20-Ball WLCSP (Pb-Free)	7"	3000 / Tape & Reel

Loading Information



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